

A B S T R A C T

An electronic assembly comprising an electronic module provided with optical interconnection and heat removal means, the heat removal means comprising a soleplate dedicated to removing heat on which the module is mounted. The interconnection means is independent of the soleplate and preferably comprises a printed circuit and an optical fiber included in the printed circuit. The optical fiber has an end put accurately in register with an optical contact of the module by a BGA type mounting of the printed circuit on the module. A BGA type mounting consists in placing with precision firstly balls on the module and secondly areas on the circuit, and then in bringing the balls and areas face to face so that the balls center themselves automatically with the areas by capillarity.